PCN Number:	20160615000				PCN Date:		06/24/2016	
Title: Datasheet for LM5122/LM5122-Q1								
Customer Contact:	PCN Manager Dept				pt:	t: Quality Services		
Change Type:								
Assembly Site		Design			Wafer	Bum	p Site	
Assembly Process		Data Sheet				r Bump Material		
Assembly Materials		Part number of	change	Щ		er Bump Process		
Mechanical Specification		Test Site		Щ		/afer Fab Site		
Packing/Shipping/Labeling		Test Process		Щ		afer Fab Materials		
1		otification Details			Wafer	fer Fab Process		
Description of Change:								
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below: Texas Instruments								
LM5122, LM5122-Q1 SNVS954G – FEBRUARY 2013 – REVISED MAY 2016					www.ti.com			
Changes from Revision F (May 2015) to Revision G Page								
Added Automotive ESD feature								
Added paragraph and second equation						21		
Changed equation							21	
Device Family		Change From	1:			Char	nge To:	
LM5122/LM5122-Q1			SNVS954F			SNVS954G		
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/lm5122-q1								
Reason for Change:								
To more accurately reflect device characteristics.								
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):								
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.								
Changes to product identification resulting from this PCN:								
None.								
Product Affected:								
LM5122MH/NOPB	LM5122M	HX/NOPB	LM5122QMI	HE/NOPB				
LM5122MHE/NOPB	LM5122QN			122QMHX/NOPB				
•	<u> </u>	*	· <u>*</u>			•		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com